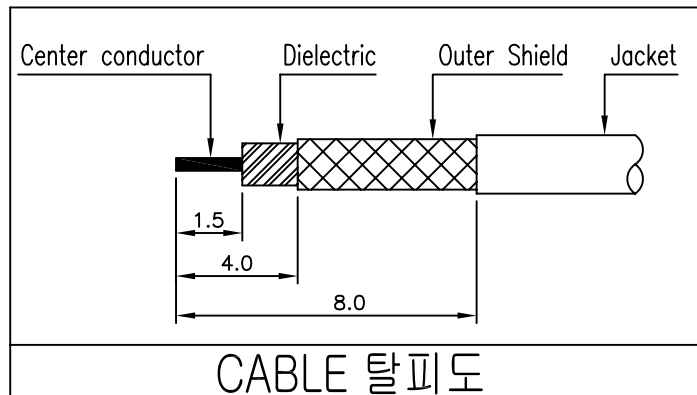
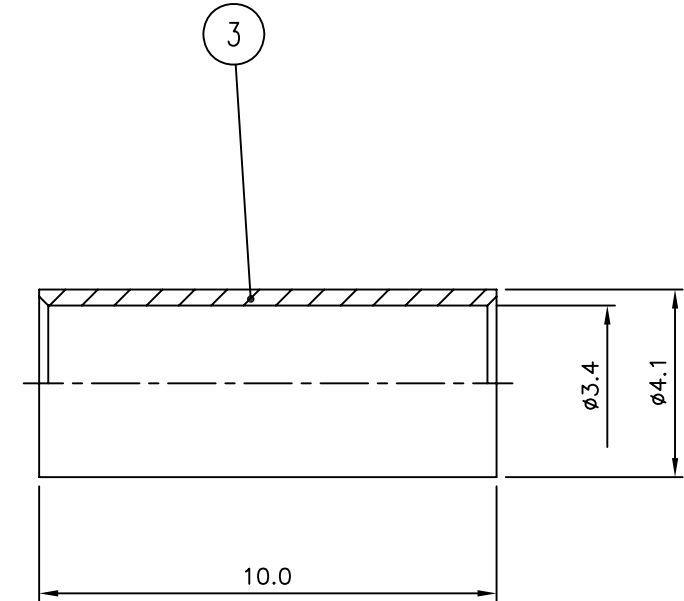
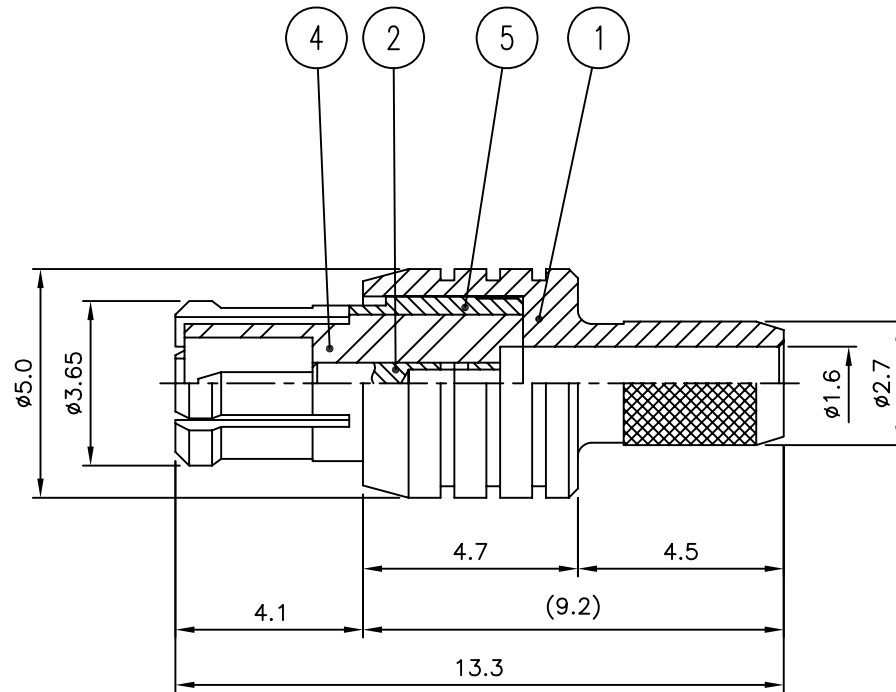


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2018.10.02.
1	커넥터 압착부 바디 부러짐 현상 방지로 인한 R추가	S.Y.EUN	S.H.KIM	2021.12.24.



5	JACK	1	BeCu C17300	Gold Plate	DJA00009-5/4
4	INSULATOR	1	TEFLON		DIN00066-N/3
3	FERRULE	1	MBsBD C3604BD-F	Nickel Plate	DFE00075-5/1
2	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT00063-5/3
1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD00030-5/3
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2021. 12. 24.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	S.H.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE MCX50 PS RG316DS
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	6/1	DWG NO. CN00023-7/7 REVISION 1 SHEET 1 of 1
		UNIT	mm	